

## EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	169	(@ad<"20030226") and 438/121, 125.ccls. and (mems or microstrucure or micromechanical or electromechanical or electricalmechanical or sensor or micro)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/08/02 19:33
L2	50	L1 and (cure\$1 or curing)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/08/02 19:34
L3	832	(@ad<"20030226") and 438/22,48, 52.ccls. and (mems or microstrucure or micromechanical or electromechanical or electricalmechanical or sensor or micro)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/08/02 20:29
L4	77	L3 and (cure\$1 or curing)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/08/02 19:34
L5	77	L4 not L2	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/08/02 20:16
L6	0	("20040166606").PN.	USPAT; USOCR	OR	OFF	2006/08/02 20:17
L7	1	("20040166606").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/08/02 20:17
L8	46	(@ad<"20030226") and 438/22,48, 52,121,125.ccls. and ((cur\$3 and (hole or aperture or recess or via or groove or channel or via or opening)) with (encapsulant or encapsulate or epoxy))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/08/02 20:41
L9	87	(@ad<"20030226") and 438/106. ccls. and ((cur\$3 and (liquid or pour)) with (encapsulant or encapsulate or epoxy))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/08/02 20:53

## EAST Search History

L10	44	L9 and polymer	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/08/02 20:46
L11	1	("5714800").PN.	USPAT; USOCR	OR	OFF	2006/08/02 20:46
L12	64	(@ad<"20030226") and 438/106. ccls. and ((capillary or viscosity) with (encapsulant or encapsulate or epoxy))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/08/02 20:55